



DEFENSE LOGISTICS AGENCY
LAND AND MARITIME
POST OFFICE BOX 3990
COLUMBUS, OH 43218-3990

September 13, 2012

Mr. Jim Keathly
QA Manager
Micropac Industries, Inc.
905 E Walnut Street
PO Box 469017
Garland, TX 75040

Dear Mr. Keathly:

Re: Notification of Qualification, Hybrid Microcircuits MIL-PRF-38534, FSC 5962, VQ (VQH-12-025067), Control Number 037278

Qualification of your processes and materials is granted effective September 12, 2012 under the current issue of the Performance Specification MIL-PRF-38534, Hybrid Microcircuits, FSC 5962. This action is a result of successful qualification in accordance with test report number 38534-3603-12.

The hybrid qualified by this report is identified in Micropac Industries Inc. VQH-42H Form 5962-93140 (53111), dated 9/12/12. Your Qualified Manufacturers List (QML) listing will appear as in Enclosure 1 and is subject to the conditions printed in Enclosure 2.

To maintain this listing, you are required to provide a retention report every twelve months. The standard reporting period is from January 1 through December 30 and your next report is due on January 31, 2013. This report is to include the processes and materials from this qualification. For additional information regarding the retention of qualification report, please see the DLA Land and Maritime-VQH published booklet Certification and Qualification Procedures for MIL-PRF-38534 Hybrid and MCM Microcircuits.

QML manufacturers shall notify the qualifying activity immediately after learning of a potential issuance of a GIDEP alert, problem advisory or major quality/reliability problem affecting QML products. Failure to provide prior notification may be grounds for removal from QML 38534.

Because we are held responsible for the accuracy and currency of this QML, please let us know if your company discontinues production utilizing this process.

If you have any questions concerning this letter, please contact Miss Schneider at (614) 692-0585.

Sincerely,

/signed/

JOSEPH GEMPERLINE
Chief
Sourcing and Qualifications Division

Enclosures

Micropac Industries, Incorporated (CAGE Code: 31757)

905 East Walnut Street, Garland, TX 75040-6696, US

Company Contact: Mr. Cecil Miller, Phone: 972-272-3571, Fax: 972-494-2281, E-mail: cmiller@micropac.com

DSCC Contact: Mr. Dan Miller, Phone: 614-692-2908, Fax: 614-692-6942, E-mail: vqh.dm@dla.mil

Quality Management (QM) Program: Non-TRB

Periodic Inspection System: Options 1 and 2

Technologies: Custom, Power, Optocouplers

Inmobiliaria San Jose De Co. Plant

Qualification Letters: VQ(VQH-04-005466), VQ(VQH-06-010381), VQ(VQH-06-011928)

Class Level Information: See Note 6/

Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: N/A

Substrate Fabrication: N/A

Assembly Information: See Note 1/

Assembly Flows: 90138

Substrate Attach: N/A

Element Attach: Conductive Epoxy, Nonconductive Epoxy

Add-on Elements: Unpackaged Die, Chip Resistors, Spacer

Wire Bonding: Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: N/A

Micropac Custom Line, Garland TX

Qualification Letters: EQ(EQC-91-178), EQ(EQC-91-647), EQ(EQC-92-183), EQ(EQC-92-258), VQ(VQH-04-006232), VQ(VQH-05-008704), VQ(VQH-05-009200), VQ(VQH-05-009466), VQ(VQH-06-011928), VQ(VQH-07-012661), VQ(VQH-07-013773)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: 90138

Substrate Fabrication: Thick Film on Alumina, 5 Conductor Level(s), Resistors

Assembly Information: See Note 1/

Assembly Flows: 90138

Substrate Attach: Nonconductive Epoxy, Solder

Element Attach: Eutectic, Conductive Epoxy, Nonconductive Epoxy

Add-on Elements: Unpackaged Die, Chip Capacitors, Chip Resistors

Wire Bonding: Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, Axial Leads, Seam Weld, 5.00 Inch Seal Perimeter, 28 Leads, Gold/Solder Lead Finish, Getter Qualified; Metal Package, Peripheral Leads, Seam Weld, 5.00 Inch Seal Perimeter, 46 Leads, Gold/Solder Lead Finish, Getter Qualified

Notes:

1/ The QML listing can be expanded provided appropriate qualification testing is performed and passed. Therefore the manufacturer may accept an order for compliant product not covered by his QML listing, but shall not ship the compliant product until the testing has been successfully completed.

2/ Package seal perimeter is listed by largest perimeter successfully tested in inches.

3/ Package lead counts are listed by maximum number of leads covered by qualification.

4/ Caution. Do not use this number for item acquisition. Item acquired to this number may not satisfy the performance requirements of the listed SMD.

5/ Inactive for new design, no longer available from manufacturer.

6/ Class E devices are devices, which meet all of the requirements of one of the other classes (K, H, or G), with some exceptions taken. Therefore any manufacturer qualified to G, H or K is eligible to produce and mark product as compliant to class E.

Micropac Industries, Incorporated (CAGE Code: 31757)

905 East Walnut Street, Garland, TX 75040-6696, US

Micropac Opto Line, Garland TX

Qualification Letters: EQ(EQC-90-624), EQ(EQC-91-188), EQ(EQC-91-466), EQ(EQC-92-120), ELS(ELSH-95-0057), ELS(ELSH-95-0444), VQ(VQH-04-006232), VQ(VQH-05-008721)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: 90138

Substrate Fabrication: Thick Film on Alumina, 2 Conductor Level(s), Resistors; Thick Film on Alumina, 1 Conductor Level(s)

Assembly Information: See Note 1/

Assembly Flows: 90138

Substrate Attach: Conductive Epoxy, Nonconductive Epoxy

Element Attach: Eutectic, Conductive Epoxy

Add-on Elements: Unpackaged Die

Wire Bonding: Gold

Package Information: See Notes 1/ 2/ 3/

Package Information: Ceramic Package, Dual-in-line, Solder Seal, 1.89 Inch Seal Perimeter, 16 Leads, Gold/Solder Lead Finish, Getter Qualified; Ceramic Package, Leadless Chip Carrier, Solder Seal, 1.60 Inch Seal Perimeter, 24 Leads, Solder Lead Finish, Getter Qualified; Metal Package, TO Can (dual base), Projection Weld, .54 Inch Seal Perimeter, 7 Leads, Gold/Solder Lead Finish, Getter Qualified

Micropac Power Line, Garland TX

Qualification Letters: EQ(EQC-90-625), EQ(EQC-91-328), EQ(EQC-91-338), EQ(EQC-92-183), EQ(EQC-92-258), ELS(ELSH-94-0496), VQ(VQH-04-006232), VQ(VQH-05-007911), VQ(VQH-05-009200), VQ(VQH-06-011765), VQ(VQH-07-013121), VQ(VQH-08-015994), VQ(VQH-12-025067)

Class Level Information: See Note 6/

Class K, Class H, Class E

Substrate Fabrication Information: See Note 1/

Substrate Fabrication Flows: 90138

Substrate Fabrication: Thick Film on Alumina, 1 Conductor Level(s), Resistors; Thick Film on Beryllia, 2 Conductor Level(s), Resistors

Assembly Information: See Note 1/

Assembly Flows: 90138

Substrate Attach: Nonconductive Epoxy, Solder

Element Attach: Conductive Epoxy, Solder, Eutectic

Add-on Elements: Unpackaged Die, Chip Capacitors

Wire Bonding: Gold, Aluminum

Package Information: See Notes 1/ 2/ 3/

Package Information: Metal Package, TO Can, Projection Weld, 2.27 Inch Seal Perimeter, 8 Leads, Gold/Solder Lead Finish, Getter Qualified; Ceramic Package, Dual-in-line, Seam Weld, 1.36 Inch Seal Perimeter, 8 Leads, Gold Lead Finish

Notes:

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- 3/ Package lead counts are listed by maximum number of leads covered by qualification.
- 4/ Caution. Do not use this number for item acquisition. Item acquired to this number may not satisfy the performance requirements of the listed SMD.
- 5/ Inactive for new design, no longer available from manufacturer.
- 6/ Class E devices are devices, which meet all of the requirements of one of the other classes (K, H, or G), with some exceptions taken. Therefore any manufacturer qualified to G, H or K is eligible to produce and mark product as compliant to class E.

CONDITIONS REGARDING QUALIFICATION APPROVAL

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.
5. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.
6. Continued qualification listing is dependent upon the manufacturer's compliance with the retention of qualification, verification of qualification, to which his products are qualified.